



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Yoshiyuki Yanagisawa et al.  
Appl. No.: 10/062,776  
Conf. No.: 3355  
Filed: January 30, 2002  
Title: DEVICE TRANSFER METHOD AND PANEL  
Art Unit: 2812  
Examiner: Savitri Mulpuri  
Docket No.: 112857-315

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Commissioner for Patents  
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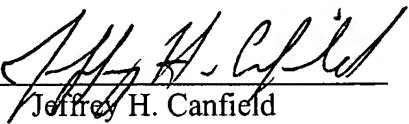
STATEMENT OF RELEVANCE

Sir:

Japanese laid open application 5-315646 discloses a method of cutting a sapphire substrate. A gallium nitride semiconductor layer formed on the sapphire substrate is cut by a dicer to form grooves deeper than the gallium nitride layer. The sapphire substrate is thinned by polishing a back surface of the substrate. Scribing lines are formed on the sapphire substrate via the grooves by a scribe. The sapphire substrate is then forcibly cut into chips by an external force. Chips can be smoothly cut without cracking and or chipping the cut plains of the sapphire substrate.

Respectfully submitted,

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